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Appln. No. 10/532,949  
Response dated December 23, 2008 to  
Reply to Final Office Action of October 3, 2008

Amendments to the Claims:

Please amend claims 1-7 and 16-19 as follows. The following listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (Currently Amended). A holding and conveyance jig for detachably holding and ~~conveyance~~ conveying a printed circuit board or a conductive material laminated plate for manufacturing said printed circuit board, said jig comprising:

5 a plate which has no electric circuit element and having has a weak-adherence adhesive pattern on a surface of the plate;  
[[and]] wherein:

10 [[a]] said printed circuit board ~~having has~~ a conductive portion and a non-conductive portion on a surface of the printed circuit board, ~~or a conductive material laminated plate for manufacturing said printed circuit board,~~ and said printed circuit board or said conductive material laminated plate ~~being~~ is placed and held on the surface of said plate, and

15 wherein said weak-adherence adhesive pattern is formed at a position corresponding to said non-conductive portion.

Claim 2 (Currently Amended). A holding and conveyance jig for detachably holding and ~~conveyance~~ conveying a printed circuit

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board or a conductive material laminated plate for manufacturing  
said printed circuit board, said jig comprising:

5           a plate which has no electric circuit element and having has  
a weak-adherence adhesive layer on a surface of the plate;

[[and]] wherein:

          [[a]] said printed circuit board ~~having has~~ a conductive  
portion and a non-conductive portion on a surface of the printed  
10   circuit board, ~~or a conductive material laminated plate for~~  
~~manufacturing said printed circuit board, and~~ said printed  
circuit board or said conductive material laminated plate ~~being~~  
is placed and held on the surface of said plate, and

~~wherein~~ a weak-adherence adhesive pattern subjected to  
15   surface roughening is formed on a surface of said weak-adherence  
adhesive layer at a position corresponding to said conductive  
portion.

Claim 3 (Currently Amended). The ~~jig for~~ holding and  
conveyance jig according to claim 1, wherein said weak-adherence  
adhesive pattern has a plurality of thickness regions differing  
in thickness from the surface of said plate.

Claim 4 (Currently Amended). The ~~jig for~~ holding and  
conveyance jig according to claim 1, wherein said weak-adherence  
adhesive pattern has a plurality of adhesive strength regions

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differing in adhesive strength.

Claim 5 (Currently Amended). The ~~jig for~~ holding and conveyance jig according to claim 2, wherein a non-adhesive pattern is formed at a position corresponding to said conductive portion on the surface of said weak-adherence adhesive layer.

Claim 6 (Currently Amended). A method of conveying a printed circuit board having a conductive portion and a non-conductive portion on a surface of the printed circuit board while detachably holding said printed circuit board on a holding  
5 and conveyance jig for holding and conveyance, said jig having in  
which a weak-adherence adhesive pattern is provided on a surface of the jig, and no electric circuit element is provided on the  
surface of the jig, the method comprising the step of:

holding said printed circuit board on the surface of said  
10 holding and conveyance jig for holding and conveyance, in a manner such that said non-conductive portion is placed by being restricted to a surface of said weak-adherence adhesive pattern.

Claim 7 (Currently Amended). A method of conveying an electroconductive material laminated plate for manufacturing a printed circuit board having a conductive portion and a non-conductive portion on a surface of the printed circuit board

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5 while detacably holding said electroconductive material laminated  
plate on a holding and conveyance jig ~~for holding and conveyance,~~  
said ~~jig having~~ in which a weak-adherence adhesive pattern  
provided on a surface of the jig, and no electric circuit  
element is provided on the surface of the jig, the method  
10 comprising the step of:

holding said electroconductive material laminated plate on  
the surface of said holding and conveyance jig ~~for holding and~~  
~~conveyance,~~ in a manner such that a portion intended for  
formation of said non-conductive portion is placed by being  
15 restricted to a surface of said weak-adherence adhesive pattern.

Claim 8 (Withdrawn). A jig for holding and conveyance  
comprising:

a plate having a weak-adherence adhesive layer on its  
surface;

5 a printed circuit board having a conductor pattern on its  
insulating substrate surface, or an electroconductive material  
laminated plate for manufacturing said printed circuit board,  
said printed circuit board or said electroconductive material  
laminated plate being placed and held on the surface of said  
10 plate,

wherein said weak-adherence adhesive layer is a  
fluorine-based resin layer.

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Claim 9 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein said fluorine-based resin layer is formed so as to hold said printed circuit board or said electroconductive material laminated plate so that a surface of  
5 said conductor pattern or an electroconductive material foil surface of said electroconductive material laminated plate is approximately parallel to the surface of said plate.

Claim 10 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein said fluorine-based resin layer has a plurality of thickness regions differing in thickness from the surface of said plate.

Claim 11 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein said fluorine-based resin layer has a plurality of adhesive strength regions differing in adhesive strength.

Claim 12 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein surface roughening is selectively performed on a region of said fluorine-based resin layer other than a holding portion for holding said printed circuit board or  
5 said electroconductive material laminated plate.

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Claim 13 (Withdrawn). The jig for holding and conveyance according to any one of claim 8, wherein a plurality of said fluorine-based resin layers are provided on the surface of said plate, and a non-adhesive material layer is provided on a  
5 non-formation portion of said fluorine-based resin layers on the surface of said plate.

Claim 14 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein said fluorine-based resin layer has a holding portion for holding said printed circuit board or said electroconductive material laminated plate, and has a  
5 non-adhesive layer on a portion other than said holding portion.

Claim 15 (Withdrawn). The jig for holding and conveyance according to claim 8, wherein said fluorine-based resin layer has a hardness (JIS-A) of 100° or lower.

Claim 16 (Currently Amended). The ~~jig~~ for holding and conveyance jig according to claim 2, wherein said weak-adherence adhesive pattern has a plurality of thickness regions differing in thickness from the surface of said plate.

Claim 17 (Currently Amended). The ~~jig~~ for holding and

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conveyance jig according to claim 2, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.

Claim 18 (Currently Amended). The ~~jig~~ for holding and conveyance jig according to claim 3, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.

Claim 19 (Currently Amended). The ~~jig~~ for holding and conveyance jig according to claim 16, wherein said weak-adherence adhesive pattern has a plurality of adhesive strength regions differing in adhesive strength.